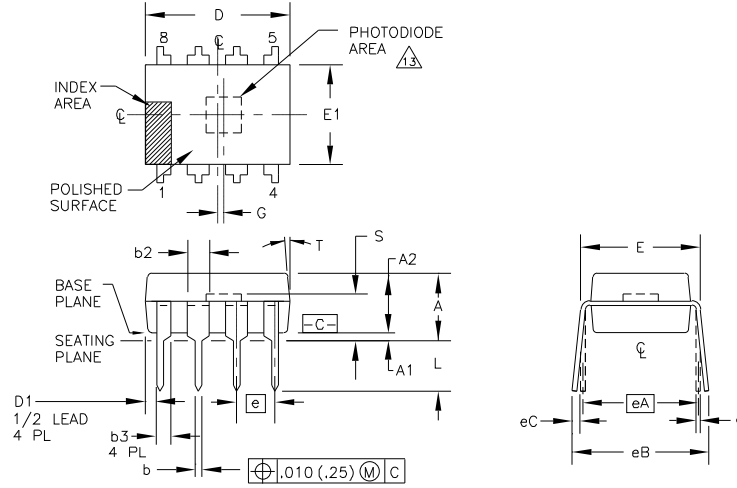


Package Number 006-5 - 8-Pin Transparent Plastic Single-Wide DIP



DIM	INCHES		MILLIMETERS		N O E
	MIN.	MAX.	MIN.	MAX.	
A	---	.165	---	4.19	3
A1	.015	---	0.38	---	3
A2	.120	.135	3.05	3.43	
b	.014	.022	0.36	0.56	
b2	.040	.050	1.02	1.27	9
b3	.030	.045	0.76	1.14	9
c	.008	.014	0.20	0.36	
D	.360	.390	9.14	9.91	4
D1	.005	---	0.13	---	4
E	.300	.325	7.62	8.26	5
E1	.238	.275	6.05	6.99	4
e	.100 BASIC		2.54 BASIC		
eA	.300 BASIC		7.63 BASIC		5
eB	---	.430	---	10.92	6

- NOTES:
- ALL DIMENSIONS ARE IN INCHES.
 - DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
 - DIMENSIONS A, A1, AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
 - D, D1, AND E1 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
 - E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM $-C-$.
 - eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
 - N IS THE MAXIMUM OF TERMINAL POSITIONS.
 - POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.

- b2 AND b3 MAXIMUM DIMENSIONS DO NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
 - DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 (0.13mm) MINIMUM.
 - A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.
 - FOR AUTOMATIC INSERTION, ANY RAISED IRREGULARITY ON THE TOP SURFACE (STEP, MESA, ETC.) SHALL BE SYMMETRICAL ABOUT THE LATERAL AND LONGITUDINAL PACKAGE CENTERLINES.
 - CENTER OF PHOTODIODE MUST BE WITHIN .010 (0.25mm) OF CENTER OF PHOTODIODE AREA.
- PACKAGE NUMBER: ZZ006-5 REV.: B
 JEDEC NUMBER: NONE



PACKAGE DRAWING

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